Pixel module production at UNL: Material flow

Module carrier
- HDI
- *visual inspection*
- on probe station
- *Fulltest*
- in curing oven
- *curing*
- Module

GelPak
- BBM

Probe Station
- *visual inspection*
- *IV curve*

Chuck for HDI
- *pick&place*

Chuck for modules
- on bonder / on gantry
- *glue application*
- *curing*
- *Encapsulation*
- *wirebonding*
- *Pretest PixelAlive*

Legend:
- ▬ Material at rest
- ＼／ Transfer
- *Test name* Quality test
- *Procedure* Process step
- → Direction of flow